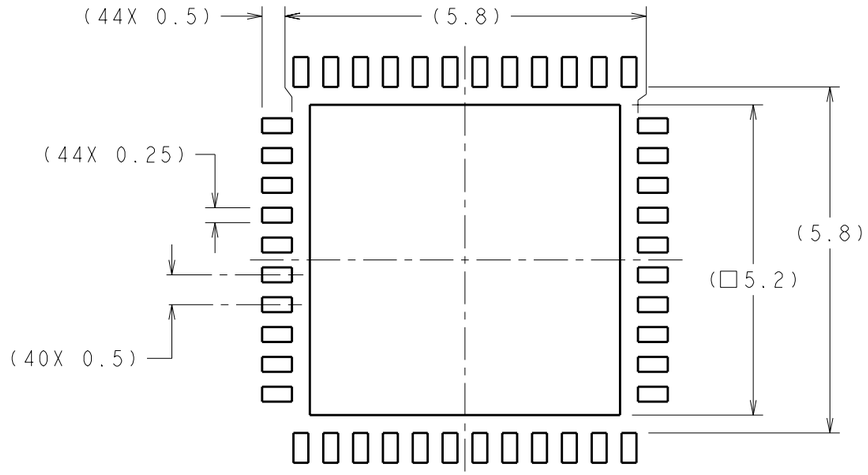
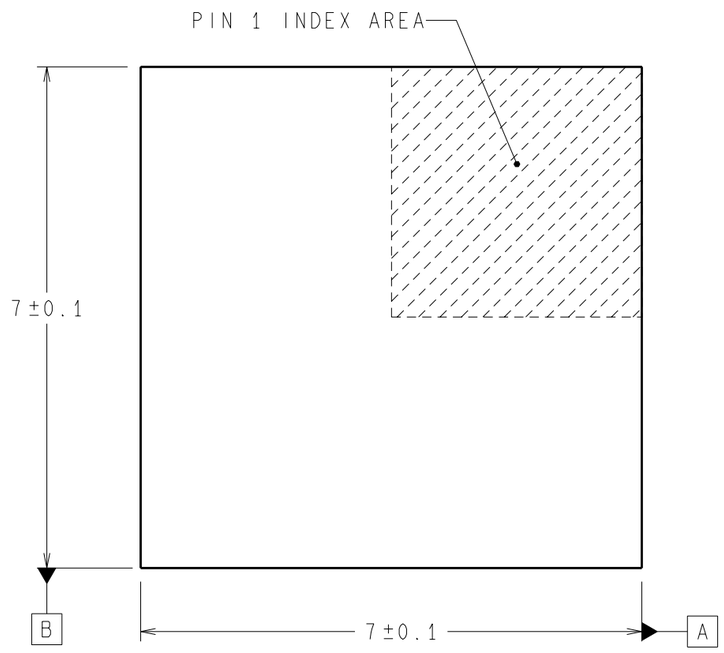
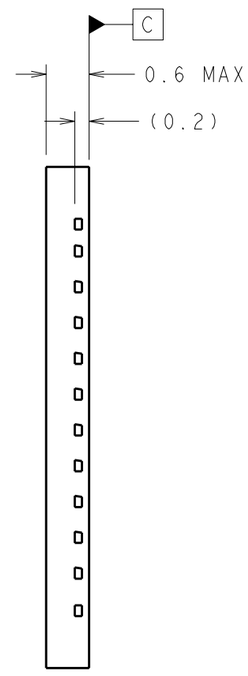
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	866	10/11/2002	TT/TL/SN
B	EXPOSED PAD DIM: 5.3 WAS 4.3; REVISE NOTES 1 & 2; LD PULL-BACK DIM: (0.1) WAS 0.1 MAX	931	04/11/2003	LY/TL/SN

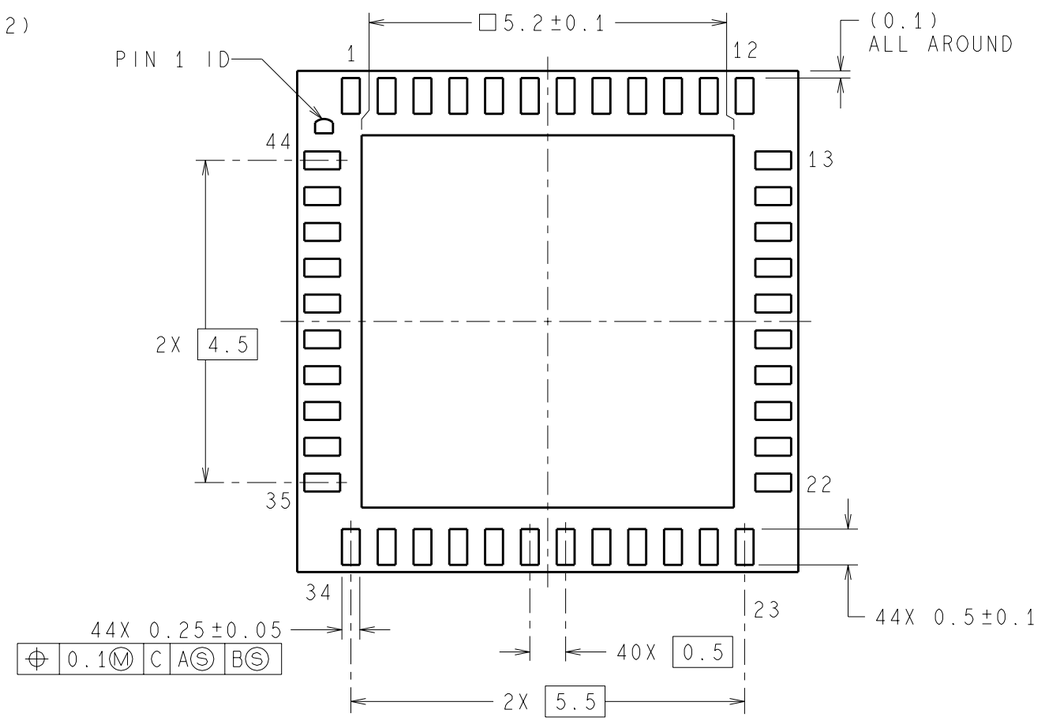


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS







NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com)

2. REFERENCE JEDEC REGISTRATION MO-220, VARIATION WKKD-5.

APPROVALS	DATE
DRAWN THERESA TAN & TL	10/11/2002
DFTG. CHK. THANH LEQUANG	04/11/2003
ENGR. CHK. S. NADARAJAH	04/11/2003

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LLP, PLASTIC, QUAD, 7 X 7 X 0.6 mm BODY, 44 LD, 0.5 mm PITCH

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-LQF44A	B

FORMERLY: N/A

SHEET 1 of 1